



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20260608000.2

**Qualification of TI Clark as an additional Assembly/Test site for select devices
Change Notification / Sample Request**

Date: June 09, 2026

To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20260608000.2
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
DRV8316CRQRGFRQ1	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20260608000.2			PCN Date:	June 09, 2026												
Title:	Qualification of TI Clark as an additional Assembly/Test site for select devices																
Customer Contact:	Change Management team		Dept:	Quality Services													
Proposed 1st Ship Date:	December 06, 2026		Sample requests accepted until:	August 08, 2026*													
*Sample requests received after August 08, 2026 will not be supported.																	
Change Type:																	
☒	Assembly Site	☐	Design	☐	Wafer Bump Material												
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process												
☐	Assembly Materials	☐	Part number change	☐	Wafer Fab Site												
☐	Mechanical Specification	☒	Test Site	☐	Wafer Fab Material												
☒	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Process												
PCN Details																	
Description of Change:																	
Texas Instruments is pleased to announce the qualification of TI Clark as an additional Assembly site for select devices. No material differences between sites.																	
<table border="1"> <tr> <td></td> <td>Current Site</td> <td>Additional Site</td> </tr> <tr> <td>Assembly/Test site</td> <td>CDAT</td> <td>CLARK</td> </tr> </table>							Current Site	Additional Site	Assembly/Test site	CDAT	CLARK						
	Current Site	Additional Site															
Assembly/Test site	CDAT	CLARK															
Qual details are provided in the Qual Data Section. Test coverage, insertions, conditions will remain consistent with current testing.																	
Reason for Change:																	
Continuity of Supply																	
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):																	
Review the SDP for full evaluation of the change based on the customer use case.																	
Impact on Environmental Ratings																	
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.																	
<table border="1"> <tr> <td>RoHS</td> <td>REACH</td> <td>Green Status</td> <td>IEC 62474</td> </tr> <tr> <td>☒ No Change</td> <td>☒ No Change</td> <td>☒ No Change</td> <td>☒ No Change</td> </tr> </table>						RoHS	REACH	Green Status	IEC 62474	☒ No Change	☒ No Change	☒ No Change	☒ No Change				
RoHS	REACH	Green Status	IEC 62474														
☒ No Change	☒ No Change	☒ No Change	☒ No Change														
Changes to product identification resulting from this PCN:																	
Assembly Site Information:																	
<table border="1"> <tr> <td>Assembly Site</td> <td>Assembly Site Origin (22L)</td> <td>Assembly Country Code (23L)</td> <td>Assembly City</td> </tr> <tr> <td>CDAT</td> <td>CDA</td> <td>CHN</td> <td>Chengdu</td> </tr> <tr> <td>TI Clark</td> <td>QAB</td> <td>PHL</td> <td>Pampanga</td> </tr> </table>						Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City	CDAT	CDA	CHN	Chengdu	TI Clark	QAB	PHL	Pampanga
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City														
CDAT	CDA	CHN	Chengdu														
TI Clark	QAB	PHL	Pampanga														
Sample Product Shipping Label (not actual product label)																	

 TEXAS INSTRUMENTS MADE IN: Malaysia 2DC: 2Q: MSL 2 / 260C / 1 YEAR MSL 1 / 235C / UNLIM SEAL DT 03/29/04 OPT: ITEM: LBL: 5A (L)T0:1750	 	(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CS0: SHE (21L) CCO: USA (22L) AS0: MLA (23L) ACO: MYS
Product Affected:		
DRV8316CRQRGFRQ1		

Qualification Report

Automotive Qualification Summary

(As per AEC-Q100 Rev. J and JEDEC Guidelines)

Approve Date 30-MARCH -2026

Product Attributes

Attributes	Qual Device:	QBS Process Reference:	QBS Package Reference:	QBS Package, Product Reference:
	DRV8316CRQRGFRQ1	DRV8873SPWPRQ1	LM70880QRRXRQ1	PDRV8316XRGFRQ1
Automotive Grade Level	Grade 1	Grade 1	Grade 1	Grade 1
Operating Temp Range (C)	-40 to 125	-40 to 125	-40 to 125	-40 to 125
Product Function	Power Management	Power Management	Power Management	Power Management
Wafer Fab Supplier	RFAB	RFAB	CFAB, CFAB, RFAB	RFAB
Assembly Site	CLARK-AT	TAI	CLARK-AT	CDAT
Package Group	QFN	TSSOP	QFN	QFN
Package Designator	RGF	PWP	PRX	RGF
Pin Count	40	24	29	40

QBS: Qual By Similarity, also known as Generic Data

Qual Device DRV8316CRQRGFRQ1 is qualified at MSL2 260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device:	QBS Process Reference:	QBS Package Reference:	QBS Package, Product Reference:
								DRV8316CRQRGFRQ1	DRV8873SPWPRQ1	LM70880QRRXRQ1	PDRV8316XRGFRQ1
Test Group A - Accelerated Environment Stress Tests											
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL2 260C	-	3/All/0	-	3/All/0	3/All/0
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL3 260C	-	-	3/All/0	-	-
HAST	A2	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	3/231/0
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Autoclave	121C/15psig	96 Hours	-	-	-	3/236/1 ¹
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Unbiased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	-

TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	3/231/0	3/231/0	3/231/0
TC-BP	A4	MIL-STD883 Method 2011	1	5	Post Temp Cycle Bond Pull	-	-	1/5/0	-	1/5/0	-
TC-SAM	A4	-	3	3	Post TC SAM	<50% delamination	-	3/9/0	-	3/36/0	-
PTC	A5	JEDEC JESD22-A105	1	45	PTC	-40/125C	1000 Cycles	-	1/45/0	-	1/45/0
Test Group B - Accelerated Lifetime Simulation Tests											
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	125C	1000 Hours	-	3/231/0	3/231/0	1/85/2 ²
ELFR	B2	AEC Q100-008	3	800	Early Life Failure Rate	125C	48 Hours	-	3/2400/0	-	-
Test Group C - Package Assembly Integrity Tests											
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	3/90/0	3/90/0	-
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	3/90/0	3/90/0	-
SD	C3	JEDEC J-STD-002	1	15	PB Solderability	>95% Lead Coverage	-	-	1/15/0	-	1/15/0
SD	C3	JEDEC J-STD-002	1	15	PB-Free Solderability	>95% Lead Coverage	-	-	1/15/0	1/15/0	1/15/0
PD	C4	JEDEC JESD22-B100 and B108	3	10	Physical Dimensions	Cpk>1.67	-	1/10/0	3/30/0	3/30/0	3/30/0
Test Group D - Die Fabrication Reliability Tests											
EM	D1	JESD61	-	-	Electromigration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
Tddb	D2	JESD35	-	-	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
HCI	D3	JESD60 & 28	-	-	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
BTI	D4	-	-	-	Bias Temperature Instability	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
SM	D5	-	-	-	Stress Migration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
Test Group E - Electrical Verification Tests											
ESD	E2	AEC Q100-002	1	3	ESD HBM	-	2000 Volts	1/3/0	1/3/0	1/3/0	1/3/0
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	1500 Volts	1/3/0	-	-	1/3/0
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	500 Volts	1/3/0	1/3/0	1/3/0	1/3/0
LU	E4	AEC Q100-004	1	3	Latch-Up	Per AEC Q100-004	-	1/6/0	1/6/0	1/3/0	1/6/0
ED	E5	AEC Q100-009	3	30	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	1/30/0	3/90/0	3/90/0	3/90/0
SC	E10	AEC Q100-012	3	10	Short Circuit Characterization	Per Q100-012	-	-	-	-	3/30/0
Additional Tests											
BLR	T1	-	-	-	Board Level Reliability - Temp Cycle	-40/125C	1000 Cycles	-	-	1/32/0	-

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Ambient Operating Temperature by Automotive Grade Level:

Grade 0 (or E): -40C to +150C

Grade 1 (or Q): -40C to +125C

Grade 2 (or T): -40C to +105C

Grade 3 (or I) : -40C to +85C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

Room/Hot/Cold : HTOL, ED

Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU

Room : AC/uHAST

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2411-044

[1]-Test marginality. 8D available

[2]-Test marginality. 8D available

Qualification Report Automotive Qualification Summary (As per AEC and JEDEC Guidelines)

Q006 QFN at Clark

Approve Date 30-MARCH -2026

Product Attributes

Attributes	Qual Device: DRV8316CRQGRFQ1	QBS Package Reference: LM70880QRRXRQ1	QBS Package, Product Reference: PDRV8316XRGFRQ1
Automotive Grade Level	Grade 1	Grade 1	Grade 1
Operating Temp Range (C)	-40 to 125	-40 to 125	-40 to 125
Product Function	Power Management	Power Management	Power Management
Wafer Fab Supplier	RFAB	CFAB, CFAB, RFAB	RFAB
Assembly Site	CLARK-AT	CLARK-AT	CDAT
Package Group	QFN	QFN	QFN
Package Designator	RGF	RRX	RGF
Pin Count	40	29	40

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: DRV8316CRQGRFQ1	QBS Reference: LM70880QRRXRQ1	QBS Reference: PDRV8316XRGFRQ1
Test Group A - Accelerated Environment Stress Tests										
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL2 260C	-	3/All/0	3/All/0	3/All/0
PC	A1.1	-	3	22	SAM Precon Pre	Review for delamination	-	3/66/0	3/66/0	3/66/0
PC	A1.2	-	3	22	SAM Precon Post	Review for delamination	-	3/66/0	3/66/0	3/66/0
HAST	A2.1	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0
HAST	A2.1.2	-	3	1	Cross Section, post bHAST, 1X	Post stress cross section	Completed	-	3/3/0	-
HAST	A2.1.3	-	3	3	Wire Bond Shear, post bHAST, 1X	Post stress	-	-	3/9/0	-
HAST	A2.1.4	-	3	3	Bond Pull over Stitch, post bHAST, 1X	Post stress	-	-	3/9/0	-
HAST	A2.1.5	-	3	3	Bond Pull over Ball, post bHAST, 1X	Post stress	-	-	3/9/0	-

HAST	A2.2	JEDEC JESD22-A110	3	70	Biased HAST	130C/85%RH	192 Hours	-	3/231/0	3/210/0
HAST	A2.2.1	-	3	22	SAM Analysis, post bHAST 2X	Review for delamination	Completed	-	3/66/0	3/66/0
HAST	A2.2.2	-	3	1	Cross Section, post bHAST, 2X	Post stress cross section	Completed	-	3/3/0	-
HAST	A2.2.3	-	3	3	Wire Bond Shear, post bHAST, 2X	Post stress	-	-	3/9/0	3/9/0
HAST	A2.2.4	-	3	3	Bond Pull over Stitch, post bHAST, 2X	Post stress	-	-	3/9/0	3/9/0
HAST	A2.2.5	-	3	3	Bond Pull over Ball, post bHAST, 2X	Post stress	-	-	3/9/0	3/9/0
TC	A4.1.1	-	3	22	SAM Analysis, post TC 1X	Review for delamination	Completed	-	3/66/0	-
TC	A4.1.2	-	3	1	Cross Section, post TC, 1X	Post stress cross section	Completed	-	3/3/0	-
TC	A4.1.3	-	3	3	Wire Bond Shear, post TC, 1X	Post stress	-	-	3/9/0	-
TC	A4.1.4	-	3	3	Bond Pull over Stitch, post TC, 1X	Post stress	-	-	3/9/0	-
TC	A4.1.5	-	3	3	Bond Pull over Ball, post TC, 1X	Post stress	-	-	3/9/0	-
TC	A4.2	JEDEC JESD22-A104 and Appendix 3	3	70	Temperature Cycle	-65C/150C	1000 Cycles	3/231/0	3/231/0	3/231/0
TC	A4.2.1	-	3	22	SAM Analysis, post TC, 2X	Review for delamination	Completed	-	3/66/0	3/66/0
TC	A4.2.2	-	3	1	Cross Section, post TC, 2X	Post stress cross section	Completed	-	3/3/0	-
TC	A4.2.3	-	3	3	Wire Bond Shear, post TC, 2X	Post stress	-	-	3/9/0	3/9/0
TC	A4.2.4	-	3	3	Bond Pull over Stitch, post TC, 2X	Post stress	-	-	3/9/0	3/9/0
TC	A4.2.5	-	3	3	Bond Pull over Ball, post TC, 2X	Post stress	-	-	3/9/0	3/9/0
PTC	A5.1	JEDEC JESD22-A105	1	45	PTC	-40/125C	1000 Cycles	-	-	1/45/0
PTC	A5.2	JEDEC JESD22-A105	1	45	PTC	-40/125C	2000 Cycles	-	-	1/45/0
HTSL	A6.1.1	-	3	1	Cross Section, post HTSL, 1X	Post stress cross section	Completed	-	3/3/0	-
HTSL	A6.2	JEDEC JESD22-A103	3	44	High Temperature Storage Life	150C	2000 Hours	-	3/135/0	3/135/0
HTSL	A6.2.1	-	3	1	Cross Section, post HTSL, 2X	Post stress cross section	Completed	-	3/3/0	-
Test Group C - Package Assembly Integrity Tests										
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	3/90/0	-
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	3/90/0	-

QBS: Qual By Similarity, also known as Generic Data

Qual Device DRV8316CRQGRFQRQ1 is qualified at MSL2 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Ambient Operating Temperature by Automotive Grade Level:

Grade 0 (or E): -40C to +150C

Grade 1 (or Q): -40C to +125C

Grade 2 (or T): -40C to +105C

Grade 3 (or I) : -40C to +85C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

Room/Hot/Cold : HTOL, ED

Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU

Room : AC/uHAST

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2411-044

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

ZVEI ID: SEM-PA-18, SEM-TF-01

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.

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